65-nm CMOS, W-band Receivers for Imaging Applications

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Table of Content

- Motivation
- Circuit Schematics
- Fabrication
- Measurement Results
- Conclusion







Motivation

- Investigation of W-band receivers in 65-nm GP CMOS
 - CMOS might provide alternatives to III-V and SiGe technology in imaging arrays:
 - Broadband (multi-GHz)

- Low noise
- Low power
 Small area
- Comparison of two LNA feedback topologies
 - Series-series feedback with inductor
 - Shunt-series feedback with transformer











LNA – Schematic



- Inductive (series-series) feedback LNA
- Input matched by L_{G} and L_{S} $\Re\{Z_{IN}\} = 2\pi f_T L_S + R_G + R_S$
- Noise impedance matched by transistor sizing and biasing







- Input matched by L_P , L_S and $M \quad \Re\{Z_{IN}\} \approx \frac{L_P}{g_m \cdot M}, \quad M = k \sqrt{L_P L_S}$
- Noise impedance matched by transistor sizing and biasing







• S_{11} , $\Gamma_{opt} < -10 \text{ dB from 74-100 GHz for both designs}$





Fabrication

- 65-nm GP/LP digital CMOS process
- 7 metal layers
- GP n-MOSFETs (80×60nm×1µm) with gate contacted on one side: f_T/f_{MAX} =170 GHz/200 GHz at V_{DS} = 0.7 V
- GP MOSFETs 30% faster than LP MOSFETs and require lower V_{GS} and V_{DS} \rightarrow lower power
- Gate leakage does not affect mm-wave performance





LNA breakouts – Die Photos



490 um x 300 um (pad) → 120 um x 170 um (core)





Mixer breakout – Die Photo



470 um x 560 um (pad) → 190 um x 160 um (core)





Receiver – Die Photos





IND-feedback Receiver XFMR-feedback Receiver 460 um x 500 um (pad) \rightarrow 160 um x 370 um (core)



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- Requires 2.2 V V_{DD} for 8 9 dB gain
- 4 5 dB below simulation



Measurements for 2nd Spin with Modified Layout

Series resistance in ground metallization of LNA was found in the first spin.

A second spin of the design was fabricated with:

- Wider metal lines in ground mesh at top level
- Increased number of vias (even between M5 and M6)
- LNA inductance values adjusted to match @ 80 GHz







• Measured gain @ $1.5 V V_{DD} = 13 dB$





• Meas. gain @ $V_{DD} = 1.5$ V is 1 - 2 dB below sims.

S₁₁ < -20 dB from 80 – 90 GHz (xfmr-feedback)





Meas. Mixer – Conversion Gain





Meas. Mixer – NF_{DSB}



- Includes ~2 dB transformer loss
- Lowest NF_{DSB} mixer at 80 90 GHz in silicon







LO @ 75 GHz due to equipment limitation



Estimated LNA NF



$$G_{LNA} = G_{RCVR} - G_{MIXER}$$
$$F_{LNA} = F_{RCVR} - \frac{F_{MIXER} - 1}{G_{LNA}}$$

LNA gain peaks at
 frequency higher than
 measured (output pad
 capacitance removed)

LNA NF₅₀ \sim 6 – 7 dB





Summary of Results

	V _{DD} [V]	LNA		IF Buffer	Receiver			
1 st Spin		P _{diss}	Gain	P _{diss}	P _{diss}	Gain	NF	S ₁₁
		[mW]	[dB]	[mW]	[mW]	[dB]	[dB]	[dB]
	1.8	38	5.8	47	95	11.6	9 – 10	< -10
	2.2	57	7.8	75	150	13.5	8 – 9	(80-95+ GHz)
Ond	1.2	24	11.1	20	48	6.1	9 – 10	10
Spin	1.5	34	13.4	30	71	13.6	7 – 8	< -10
	1.8	48	14.9	45	104	17.7	6 – 7	(74-95* GHZ)

 Dramatic increase in performance just with better top-level ground mesh and vias

• ~ $\frac{1}{2}$ of P_{diss} used in IF buffer to drive 50 Ω off-chip

Conclusion

- 74 94 GHz receiver with 8 dB NF and 13 dB gain demonstrated in 65 nm GP CMOS technology.
- Inductive-feedback and transformer-feedback LNA topologies presented:
 - Similar performance achieved by different matching procedures
- Layout style significantly affects circuit performance.
- Post-layout simulation at top-level, with ground mesh must be carried out.





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LO power



